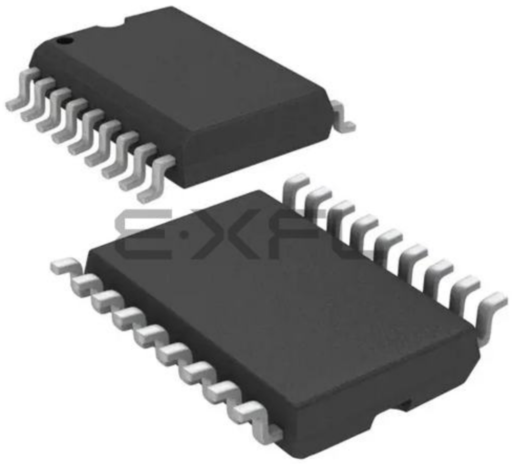

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	128 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lce625t-04e-so

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We appreciate your assistance in making this a better document.

2.0 PIC16CE62X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements the proper device option can be selected using the information in the PIC16CE62X Product Identification System section at the end of this data sheet. When placing orders, please use this page of the data sheet to specify the correct part number.

2.1 UV Erasable Devices

The UV erasable version, offered in the CERDIP package is optimal for prototype development and pilot programs. This version can be erased and reprogrammed to any of the oscillator modes.

Microchip's PICSTART® and PRO MATE® programmers both support programming of the PIC16CE62X.

2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers who need the flexibility for frequent code updates and small volume applications. In addition to the program memory, the configuration bits must also be programmed.

2.3 Quick-Turn-Programming (QTP) Devices

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who chose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your Microchip Technology sales office for more details.

2.4 Serialized Quick-Turn-Programming (SQTP℠) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number which can serve as an entry-code, password or ID number.

3.1 Clocking Scheme/Instruction Cycle

The clock input (OSC1/CLKIN pin) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3 and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow is shown in Figure 3-2.

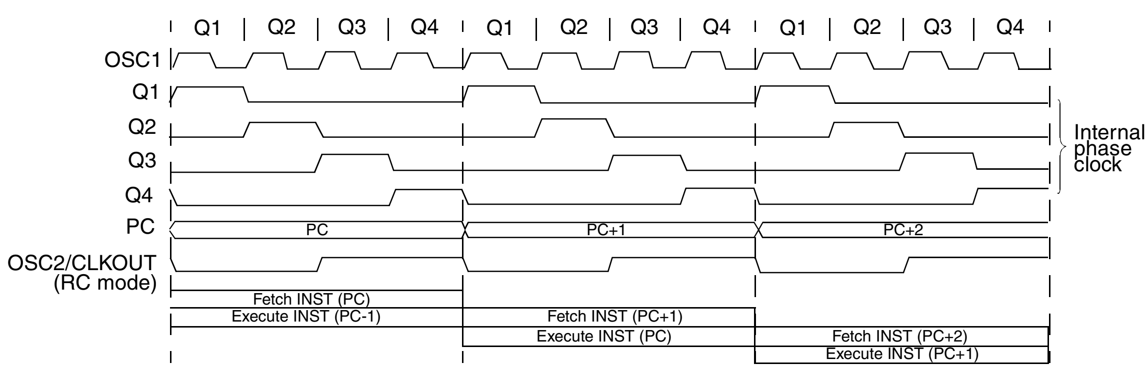
3.2 Instruction Flow/Pipelining

An “Instruction Cycle” consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle, while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (i.e., `GOTO`) then two cycles are required to complete the instruction (Example 3-1).

A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the “Instruction Register (IR)” in cycle Q1. This instruction is then decoded and executed during the Q2, Q3, and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 3-2: CLOCK/INSTRUCTION CYCLE



EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW

`1. MOVLW 55h`	Fetch 1	Execute 1				
`2. MOVWF PORTB`		Fetch 2	Execute 2			
`3. CALL SUB_1`			Fetch 3	Execute 3		
`4. BSF PORTA, BIT3`				Fetch 4	Flush	
`5. Instruction @ address SUB_1`					Fetch SUB_1	Execute SUB_1

All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is “flushed” from the pipeline, while the new instruction is being fetched and then executed.

4.2.2.6 PCON REGISTER

The PCON register contains flag bits to differentiate between a Power-on Reset, an external $\overline{\text{MCLR}}$ reset, WDT reset or a Brown-out Reset.

> **Note:** $\overline{\text{BOD}}$ is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if $\overline{\text{BOD}}$ is cleared, indicating a brown-out has occurred. The $\overline{\text{BOD}}$ status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (by programming BODEN bit in the configuration word).

REGISTER 4-6: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	$\overline{\text{POR}}$	$\overline{\text{BOD}}$
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
-n = Value at POR reset
-x = Unknown at POR reset

bit 7-2: **Unimplemented:** Read as '0'

bit 1: **$\overline{\text{POR}}$**: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **$\overline{\text{BOD}}$**: Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

5.2 PORTB and TRISB Registers

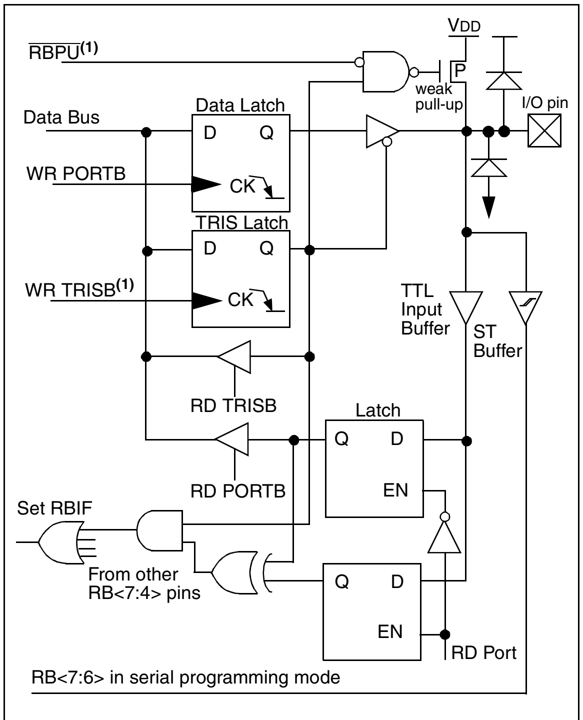
PORTB is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISB. A '1' in the TRISB register puts the corresponding output driver in a high impedance mode. A '0' in the TRISB register puts the contents of the output latch on the selected pin(s).

Reading PORTB register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

Each of the PORTB pins has a weak internal pull-up ($\approx$200 μA typical). A single control bit can turn on all the pull-ups. This is done by clearing the $\overline{\text{RBPU}}$ (OPTION<7>) bit. The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on Power-on Reset.

Four of PORTB's pins, RB<7:4>, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB<7:4> pin configured as an output is excluded from the interrupt on change comparison). The input pins of RB<7:4> are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB<7:4> are OR'ed together to generate the RBIF interrupt (flag latched in INTCON<0>).

FIGURE 5-5: BLOCK DIAGRAM OF RB<7:4> PINS



Note 1: TRISB = 1 enables weak pull-up if $\overline{\text{RBPU}}$ = '0' (OPTION<7>).

This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

a) Any read or write of PORTB. This will end the mismatch condition.

b) Clear flag bit RBIF.

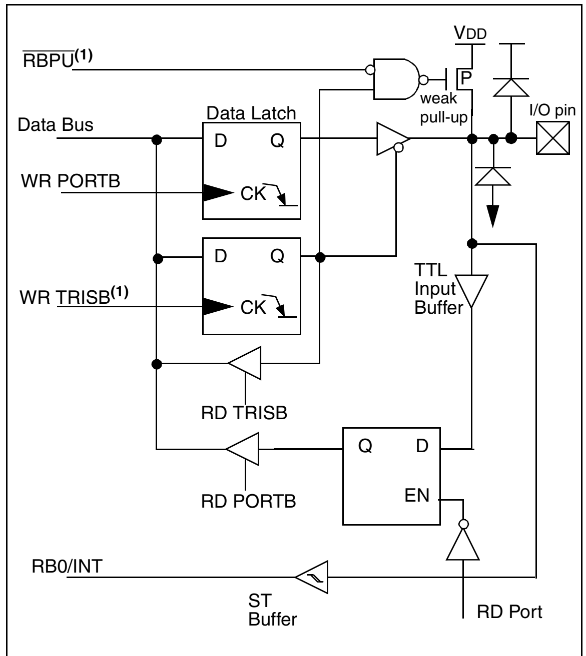
A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins allow easy interface to a key pad and make it possible for wake-up on key-depression. (See AN552, "Implementing Wake-Up on Key Strokes".)

> **Note:** If a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then the RBIF interrupt flag may not get set.

The interrupt on change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt on change feature.

FIGURE 5-6: BLOCK DIAGRAM OF RB<3:0> PINS



Note 1: TRISB = 1 enables weak pull-up if $\overline{\text{RBPU}}$ = '0' (OPTION<7>).

6.0 EEPROM PERIPHERAL OPERATION

The PIC16CE623/624/625 each have 128 bytes of EEPROM data memory. The EEPROM data memory supports a bi-directional, 2-wire bus and data transmission protocol. These two-wires are serial data (SDA) and serial clock (SCL), and are mapped to bit1 and bit2, respectively, of the EEINTF register (SFR 90h). In addition, the power to the EEPROM can be controlled using bit0 (EEVDD) of the EEINTF register. For most applications, all that is required is calls to the following functions:

```
; Byte_Write: Byte write routine
;       Inputs: EEPROM Address     EEADDR
;               EEPROM Data        EEDATA
;       Outputs:    Return 01 in W if OK, else
;                   return 00 in W
;
; Read_Current: Read EEPROM at address
currently held by EE device.
;       Inputs: NONE
;       Outputs:    EEPROM Data    EEDATA
;                   Return 01 in W if OK, else
;                   return 00 in W
;
; Read_Random: Read EEPROM byte at supplied
; address
;       Inputs: EEPROM Address     EEADDR
;       Outputs:    EEPROM Data    EEDATA
;                   Return 01 in W if OK,
;                   else return 00 in W
```

The code for these functions is available on our web site (www.microchip.com). The code will be accessed by either including the source code FL62XINC.ASM or by linking FLASH62X.ASM. FLASH62.IMC provides external definition to the calling program.

6.0.1 SERIAL DATA

SDA is a bi-directional pin used to transfer addresses and data into and data out of the memory.

For normal data transfer, SDA is allowed to change only during SCL low. Changes during SCL high are reserved for indicating the START and STOP conditions.

6.0.2 SERIAL CLOCK

This SCL input is used to synchronize the data transfer to and from the memory.

6.0.3 EEINTF REGISTER

The EEINTF register (SFR 90h) controls the access to the EEPROM. Register 6-1 details the function of each bit. User code must generate the clock and data signals.

REGISTER 6-1: EEINTF REGISTER (ADDRESS 90h)

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1
—	—	—	—	—	EESCL	EESDA	EEVDD
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as ‘0’
- n = Value at POR reset

bit 7-3: **Unimplemented:** Read as '0'

bit 2: **EESCL**: Clock line to the EEPROM
1 = Clock high
0 = Clock low

bit 1: **EESDA**: Data line to EEPROM
1 = Data line is high (pin is tri-stated, line is pulled high by a pull-up resistor)
0 = Data line is low

bit 0: **EEVDD**: VDD control bit for EEPROM
1 = VDD is turned on to EEPROM
0 = VDD is turned off to EEPROM (all pins are tri-stated and the EEPROM is powered down)

Note: EESDA, EESCL and EEVDD will read ‘0’ if EEVDD is turned off.

FIGURE 6-1: DATA TRANSFER SEQUENCE ON THE SERIAL BUS

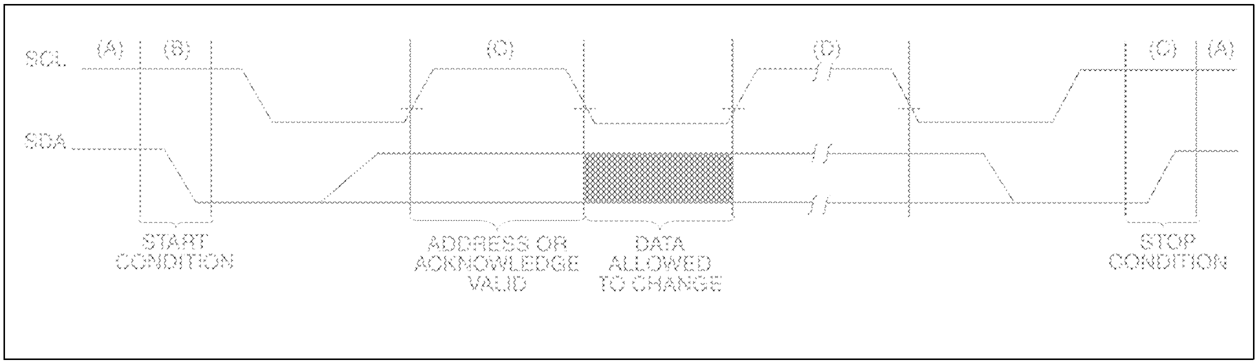
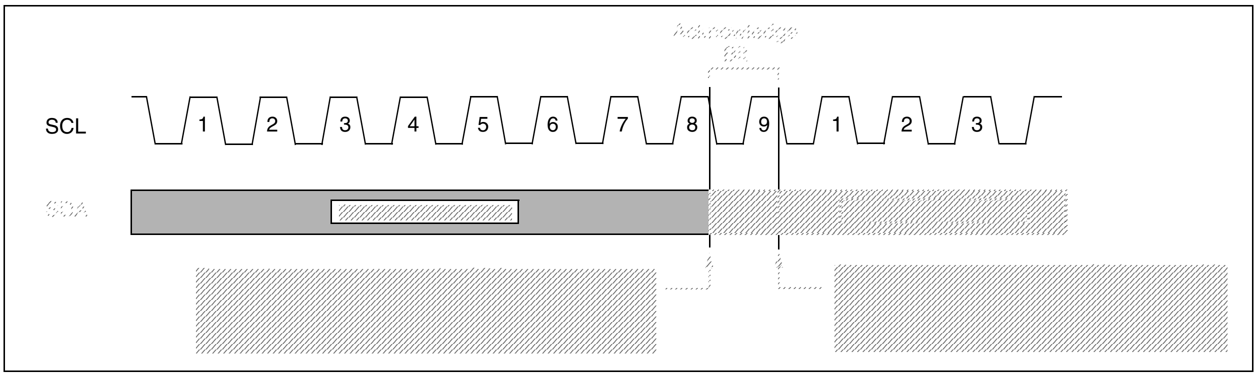


FIGURE 6-2: ACKNOWLEDGE TIMING



6.2 Device Addressing

After generating a START condition, the processor transmits a control byte consisting of a EEPROM address and a Read/$\overline{\text{Write}}$ bit that indicates what type of operation is to be performed. The EEPROM address consists of a 4-bit device code (1010) followed by three don't care bits.

The last bit of the control byte determines the operation to be performed. When set to a one, a read operation is selected, and when set to a zero, a write operation is selected. (Figure 6-3). The bus is monitored for its corresponding EEPROM address all the time. It generates an acknowledge bit if the EEPROM address was true and it is not in a programming mode.

FIGURE 6-3: CONTROL BYTE FORMAT

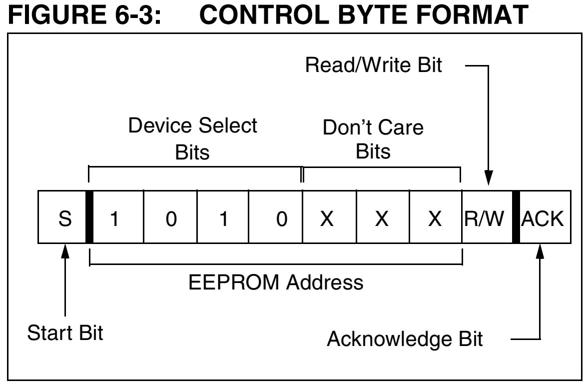


FIGURE 6-7: CURRENT ADDRESS READ

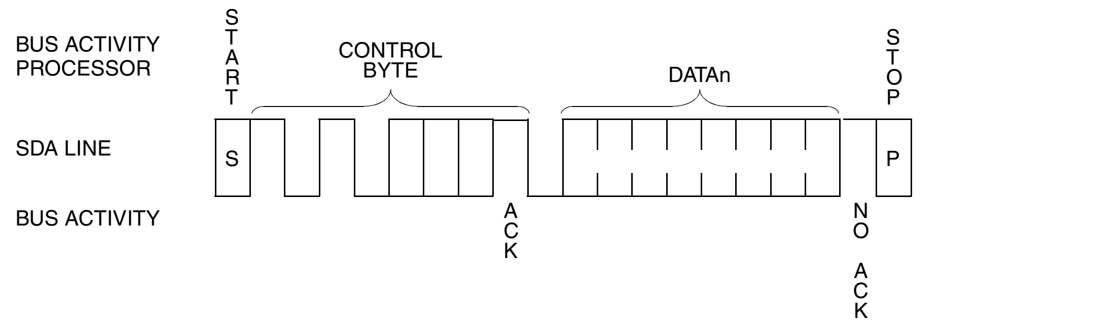


FIGURE 6-8: RANDOM READ

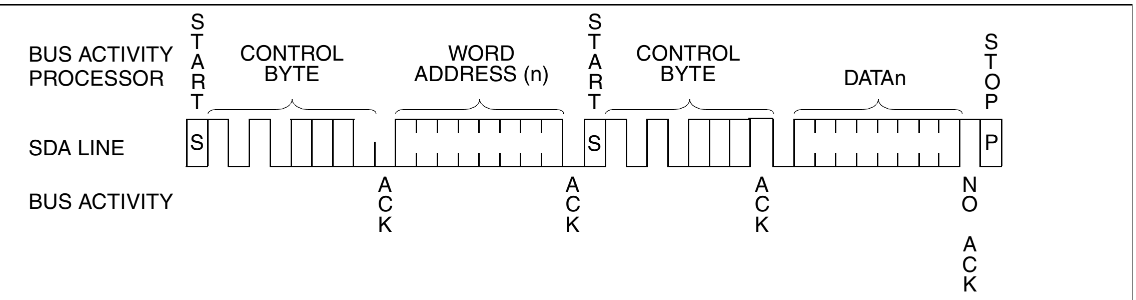
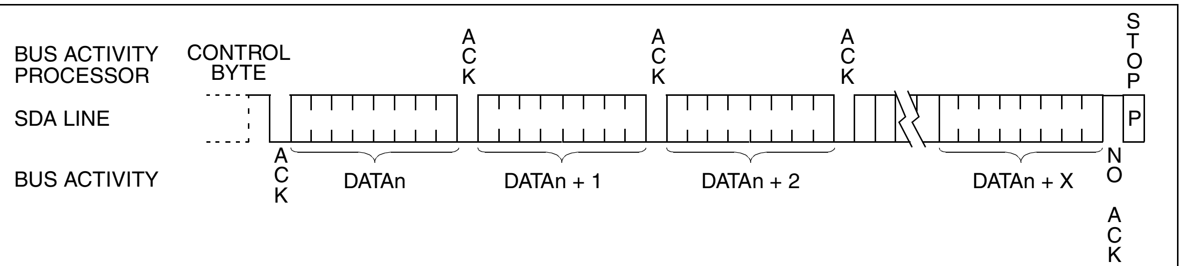


FIGURE 6-9: SEQUENTIAL READ



7.0 TIMER0 MODULE

The Timer0 module timer/counter has the following features:

- 8-bit timer/counter
- Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
- Interrupt on overflow from FFh to 00h
- Edge select for external clock

Figure 7-1 is a simplified block diagram of the Timer0 module.

Timer mode is selected by clearing the T0CS bit (OPTION<5>). In timer mode, the TMR0 will increment every instruction cycle (without prescaler). If Timer0 is written, the increment is inhibited for the following two cycles (Figure 7-2 and Figure 7-3). The user can work around this by writing an adjusted value to TMR0.

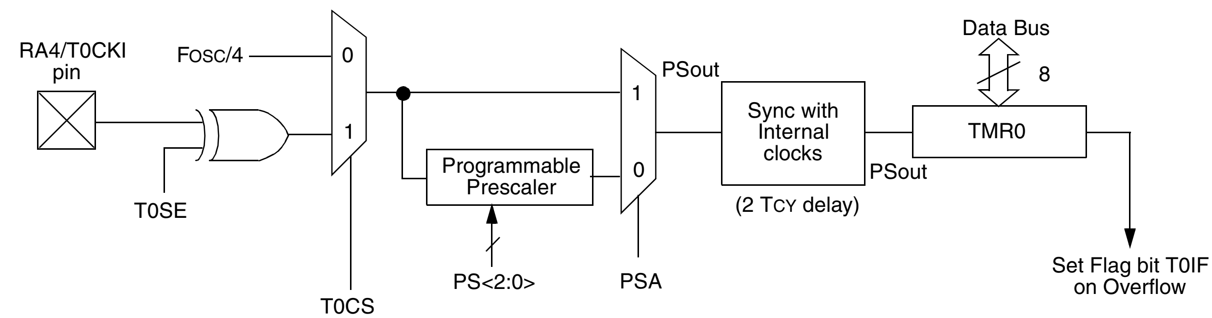
Counter mode is selected by setting the T0CS bit. In this mode Timer0 will increment either on every rising or falling edge of pin RA4/T0CKI. The incrementing edge is determined by the source edge (T0SE) control bit (OPTION<4>). Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 7.2.

The prescaler is shared between the Timer0 module and the Watchdog Timer. The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale value of 1:2, 1:4, ..., 1:256 are selectable. Section 7.3 details the operation of the prescaler.

7.1 Timer0 Interrupt

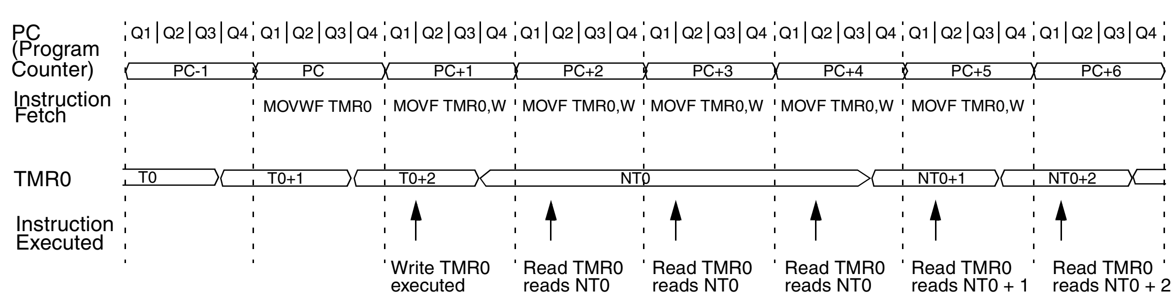
Timer0 interrupt is generated when the TMR0 register timer/counter overflows from FFh to 00h. This overflow sets the T0IF bit. The interrupt can be masked by clearing the T0IE bit (INTCON<5>). The T0IF bit (INTCON<2>) must be cleared in software by the Timer0 module interrupt service routine before re-enabling this interrupt. The Timer0 interrupt cannot wake the processor from SLEEP since the timer is shut off during SLEEP. See Figure 7-4 for Timer0 interrupt timing.

FIGURE 7-1: TIMER0 BLOCK DIAGRAM



Note 1: Bits T0SE, T0CS, PS2, PS1, PS0 and PSA are located in the OPTION register.
2: The prescaler is shared with Watchdog Timer (Figure 7-6)

FIGURE 7-2: TIMER0 (TMR0) TIMING: INTERNAL CLOCK/NO PRESCALER



NOTES:

8.6 Comparator Interrupts

The comparator interrupt flag is set whenever there is a change in the output value of either comparator. Software will need to maintain information about the status of the output bits, as read from CMCON<7:6>, to determine the actual change that has occurred. The CMIF bit, PIR1<6>, is the comparator interrupt flag. The CMIF bit must be reset by clearing '0'. Since it is also possible to write a '1' to this register, a simulated interrupt may be initiated.

The CMIE bit (PIE1<6>) and the PEIE bit (INTCON<6>) must be set to enable the interrupt. In addition, the GIE bit must also be set. If any of these bits are clear, the interrupt is not enabled, though the CMIF bit will still be set if an interrupt condition occurs.

Note:	If a change in the CMCON register (C1OUT or C2OUT) should occur when a read operation is being executed (start of the Q2 cycle), then the CMIF (PIR1<6>) interrupt flag may not get set.

The user, in the interrupt service routine, can clear the interrupt in the following manner:

a) Any read or write of CMCON. This will end the mismatch condition.

b) Clear flag bit CMIF.

A mismatch condition will continue to set flag bit CMIF. Reading CMCON will end the mismatch condition, and allow flag bit CMIF to be cleared.

8.7 Comparator Operation During SLEEP

When a comparator is active and the device is placed in SLEEP mode, the comparator remains active and the interrupt is functional if enabled. This interrupt will wake-up the device from SLEEP mode when enabled. While the comparator is powered-up, higher sleep currents than shown in the power down current specification will occur. Each comparator that is operational will consume additional current as shown in the comparator specifications. To minimize power consumption while in SLEEP mode, turn off the comparators, CM<2:0> = 111, before entering sleep. If the device wakes-up from sleep, the contents of the CMCON register are not affected.

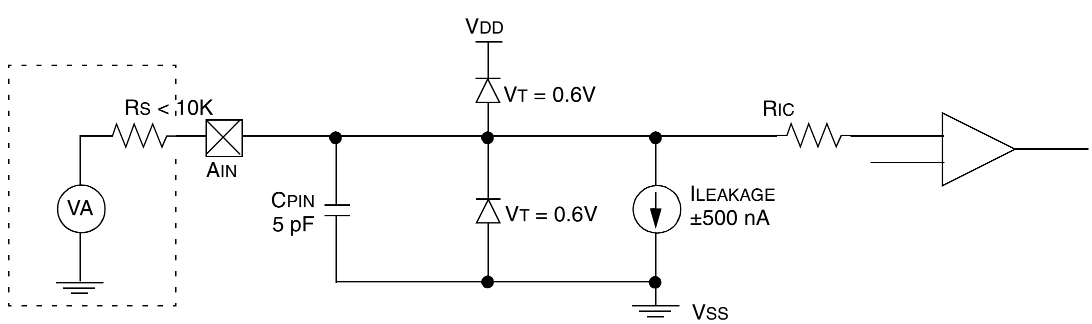
8.8 Effects of a RESET

A device reset forces the CMCON register to its reset state. This forces the comparator module to be in the comparator reset mode, CM<2:0> = 000. This ensures that all potential inputs are analog inputs. Device current is minimized when analog inputs are present at reset time. The comparators will be powered-down during the reset interval.

8.9 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 8-4. Since the analog pins are connected to a digital output, they have reverse biased diodes to V_{DD} and V_{SS}. The analog input therefore, must be between V_{SS} and V_{DD}. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up may occur. A maximum source impedance of 10 kΩ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

FIGURE 8-4: ANALOG INPUT MODEL



Legend		
	C_{PIN}	= Input capacitance
	V_T	= Threshold voltage
	$I_{LEAKAGE}$	= Leakage current at the pin due to various junctions
	R_{IC}	= Interconnect resistance
	R_S	= Source impedance
	VA	= Analog voltage

TABLE 10-5: INITIALIZATION CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	000h	0001 1xxx	---- --0x
$\overline{\text{MCLR}}$ reset during normal operation	000h	000u uuuu	---- --uu
$\overline{\text{MCLR}}$ reset during SLEEP	000h	0001 0uuu	---- --uu
WDT reset	000h	0000 uuuu	---- --uu
WDT Wake-up	PC + 1	uuu0 0uuu	---- --uu
Brown-out Reset	000h	000x xuuu	---- --u0
Interrupt Wake-up from SLEEP	PC + 1(1)	uuu1 0uuu	---- --uu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as ‘0’.

Note 1: When the wake-up is due to an interrupt and global enable bit, GIE is set and the PC is loaded with the interrupt vector (0004h) after execution of PC+1.

TABLE 10-6: INITIALIZATION CONDITION FOR REGISTERS

Register	Address	Power-on Reset	• $\overline{\text{MCLR}}$ Reset during normal operation • $\overline{\text{MCLR}}$ Reset during SLEEP • WDT Reset • Brown-out Reset (1)	• Wake-up from SLEEP through interrupt • Wake-up from SLEEP through WDT time-out
W	-	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	00h	-	-	-
TMR0	01h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	02h	0000 0000	0000 0000	PC + 1(3)
STATUS	03h	0001 1xxx	000q quuu(4)	uuuq quuu(4)
FSR	04h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	05h	---x xxxx	---u uuuu	---u uuuu
PORTB	06h	xxxx xxxx	uuuu uuuu	uuuu uuuu
CMCON	1Fh	00-- 0000	00-- 0000	uu-- uuuu
PCLATH	0Ah	---0 0000	---0 0000	---u uuuu
INTCON	0Bh	0000 000x	0000 000u	uuuu uqqq(2)
PIR1	0Ch	-0-- ----	-0-- ----	-q-- ----(2,5)
OPTION	81h	1111 1111	1111 1111	uuuu uuuu
TRISA	85h	---1 1111	---1 1111	---u uuuu
TRISB	86h	1111 1111	1111 1111	uuuu uuuu
PIE1	8Ch	-0-- ----	-0-- ----	-u-- ----
PCON	8Eh	---- --0x	---- --uq(1,6)	---- --uu
EEINTF	90h	---- -111	---- -111	---- -111
VRCON	9Fh	000- 0000	000- 0000	uuu- uuuu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as ‘0’,q = value depends on condition.

Note 1: If V_{DD} goes too low, Power-on Reset will be activated and registers will be affected differently.

2: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).

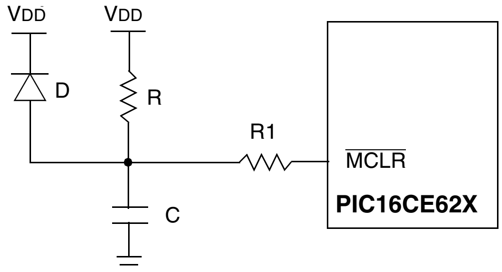
3: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

4: See Table 10-5 for reset value for specific condition.

5: If wake-up was due to comparator input changing , then bit 6 = 1. All other interrupts generating a wake-up will cause bit 6 = u.

6: If reset was due to brown-out, then PCON bit 0 = 0. All other resets will cause bit 0 = u.

FIGURE 10-11: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)

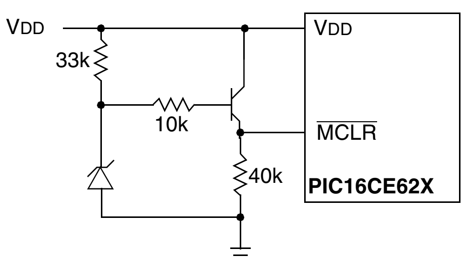


Note 1: External power-on reset circuit is required only if VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device's electrical specification.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into $\overline{\text{MCLR}}$ from external capacitor C in the event of $\overline{\text{MCLR}}$/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

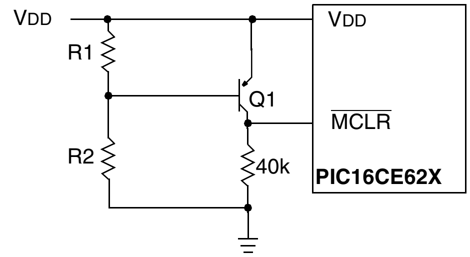
FIGURE 10-12: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 1



Note 1: This circuit will activate reset when VDD goes below (Vz + 0.7V) where Vz = Zener voltage.

2: Internal Brown-out Reset circuitry should be disabled when using this circuit.

FIGURE 10-13: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 2



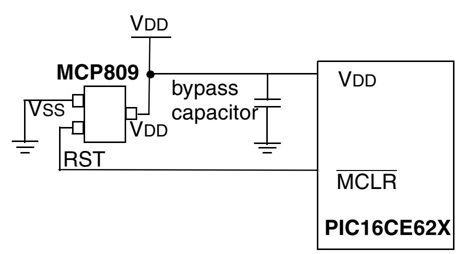
Note 1: This brown-out circuit is less expensive, albeit less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$V_{DD} \times \frac{R1}{R1 + R2} = 0.7\ V$$

2: Internal brown-out detection should be disabled when using this circuit.

3: Resistors should be adjusted for the characteristics of the transistor.

FIGURE 10-14: EXTERNAL BROWN-OUT PROTECTION CIRCUIT 3



This brown-out protection circuit employs Microchip Technology's MCP809 microcontroller supervisor. The MCP8XX and MCP1XX families of supervisors provide push-pull and open collector outputs with both high and low active reset pins. There are 7 different trip point selections to accommodate 5V and 3V systems.

GOTO — Unconditional Branch

Syntax: [*label*] GOTO k

Operands: $0 \leq k \leq 2047$

Operation: $k \rightarrow$ PC<10:0>
PCLATH<4:3> $\rightarrow$ PC<12:11>

Status Affected: None

Encoding:

10	1kkk	kkkk	kkkk

Description: `GOTO` is an unconditional branch. The eleven bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. `GOTO` is a two-cycle instruction.

Words: 1

Cycles: 2

Example

```
GOTO THERE
```

After Instruction
PC = Address `THERE`

INCF — Increment f

Syntax: [*label*] INCF f,d

Operands: $0 \leq f \leq 127$
$d \in [0,1]$

Operation: (f) + 1 $\rightarrow$ (dest)

Status Affected: Z

Encoding:

00	1010	dfff	ffff

Description: The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.

Words: 1

Cycles: 1

Example

```
INCF    CNT, 1
```

Before Instruction
CNT = 0xFF
Z = 0
After Instruction
CNT = 0x00
Z = 1

INCFSZ — Increment f, Skip if 0

Syntax: [*label*] INCFSZ f,d

Operands: $0 \leq f \leq 127$
$d \in [0,1]$

Operation: (f) + 1 $\rightarrow$ (dest), skip if result = 0

Status Affected: None

Encoding:

00	1111	dfff	ffff

Description: The contents of register 'f' are incremented. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is placed back in register 'f'.
If the result is 0, the next instruction, which is already fetched, is discarded. A `NOP` is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example

```
HERE      INCFSZ    CNT,  1
          GOTO      LOOP
CONTINUE  •
          •
          •
```

Before Instruction
PC = address `HERE`
After Instruction
CNT = CNT + 1
if CNT= 0,
PC = address `CONTINUE`
if CNT≠ 0,
PC = address `HERE +1`

IORLW — Inclusive OR Literal with W

Syntax: [*label*] IORLW k

Operands: $0 \leq k \leq 255$

Operation: (W) .OR. k $\rightarrow$ (W)

Status Affected: Z

Encoding:

11	1000	kkkk	kkkk

Description: The contents of the W register are OR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example

```
IORLW   0x35
```

Before Instruction
W = 0x9A
After Instruction
W = 0xBF
Z = 1

TABLE 12-1: DEVELOPMENT TOOLS FROM MICROCHIP

		PIC12CXXX	PIC14000	PIC16C5X	PIC16C6X	PIC16CXXX	PIC16F62X	PIC16C7X	PIC16C7XX	PIC16C8X	PIC16F8XX	PIC16C9XX	PIC17C4X	PIC17C7XX	PIC18CXX2	24CXX/ 25CXX/ 93CXX	HCSXXX	MCRFXXX	MCP2510
Software Tools	MPLAB® Integrated Development Environment	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓				
	MPLAB® C17 Compiler												✓	✓					
	MPLAB® C18 Compiler														✓				
	MPASM/MPLINK	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Emulators	MPLAB®-ICE	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓				
	PICMASTER/PICMASTER-CE	✓	✓	✓	✓	✓		✓	✓	✓		✓	✓	✓					
	ICEPIC™ Low-Cost In-Circuit Emulator	✓		✓	✓	✓		✓	✓	✓		✓							
Debugger	MPLAB®-ICD In-Circuit Debugger				✓*			✓*			✓								
Programmers	PICSTART®Plus Low-Cost Universal Dev. Kit	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓				
	PRO MATE® II Universal Programmer	✓	✓	✓	✓	✓	✓**	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓		
Demo Boards and Eval Kits	SIMICE	✓		✓															
	PICDEM-1			✓		✓		✓†		✓			✓						
	PICDEM-2				✓†			✓†							✓				
	PICDEM-3											✓							
	PICDEM-14A		✓																
	PICDEM-17													✓					
	KEELOQ® Evaluation Kit																✓		
	KEELOQ Transponder Kit																✓		
	microID™ Programmer's Kit																	✓	
	125 kHz microID Developer's Kit																	✓	
	125 kHz Anticollision microID Developer's Kit																	✓	
	13.56 MHz Anticollision microID Developer's Kit																	✓	
	MCP2510 CAN Developer's Kit																		✓

* Contact the Microchip Technology Inc. web site at www.microchip.com for information on how to use the MPLAB®-ICD In-Circuit Debugger (DV164001) with PIC16C62, 63, 64, 65, 72, 73, 74, 76, 77
** Contact Microchip Technology Inc. for availability date.
† Development tool is available on select devices.

13.2 DC CHARACTERISTICS: PIC16LCE62X-04 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature –40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial and –40°C ≤ TA ≤ +125°C for extended				
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	Supply Voltage	2.5	–	5.5	V	See Figure 13-1 through Figure 13-3
D002	VDR	RAM Data Retention Voltage (Note 1)	–	1.5*	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	–	VSS	–	V	See section on power-on reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	.05*	–	–	V/ms	See section on power-on reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D010	IDD	Supply Current (Note 2)	– – –	1.2 – 35	2.0 1.1 70	mA mA µA	FOSC = 4 MHz, VDD = 5.5V, WDT disabled, XT osc mode, (Note 4)* FOSC = 4 MHz, VDD = 2.5V, WDT disabled, XT osc mode, (Note 4) FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP osc mode
D020	IPD	Power Down Current (Note 3)	– – – –	– – – –	2.0 2.2 9.0 15	µA µA µA µA	VDD = 2.5V VDD = 3.0V* VDD = 5.5V VDD = 5.5V Extended
D022 D022A D023 D023A	ΔIWDT ΔIBOR ΔICOMP ΔIVREF ΔIEE Write ΔIEE Read ΔIEE ΔIEE	WDT Current (Note 5) Brown-out Reset Current (Note 5) Comparator Current for each Comparator (Note 5) VREF Current (Note 5) Operating Current Operating Current Standby Current Standby Current	– – – – – – – –	6.0 75 30 80	10 12 125 60 135 3 1 30 100	µA µA µA µA µA mA mA µA µA	VDD=4.0V (125°C) $\overline{\text{BOD}}$ enabled, VDD = 5.0V VDD = 4.0V VDD = 4.0V VCC = 5.5V, SCL = 400 kHz VCC = 3.0V, EE VDD = VCC VCC = 3.0V, EE VDD = VCC
1A	FOSC	LP Oscillator Operating Frequency RC Oscillator Operating Frequency XT Oscillator Operating Frequency HS Oscillator Operating Frequency	0 0 0 0	— — — —	200 4 4 20	kHz MHz MHz MHz	All temperatures All temperatures All temperatures All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
$\overline{\text{OSC1}}$ = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula Ir = VDD/2Rext (mA) with Rext in kΩ.

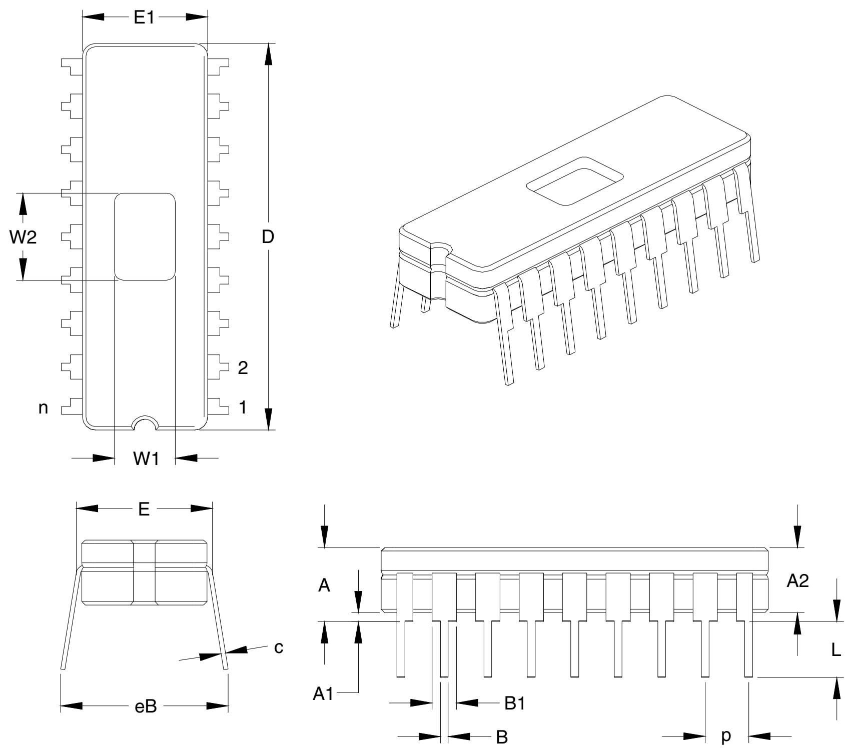
5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

14.0 PACKAGING INFORMATION

18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

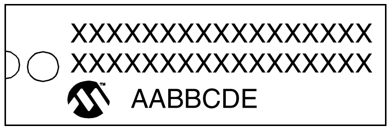


Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

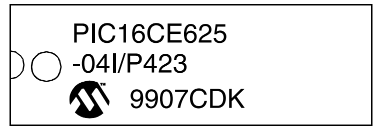
*Controlling Parameter
JEDEC Equivalent: MO-036
Drawing No. C04-010

14.1 Package Marking Information

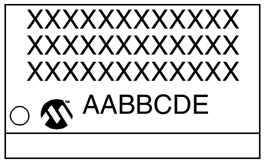
18-Lead PDIP



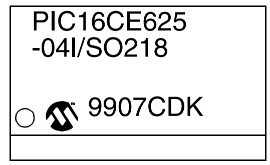
Example



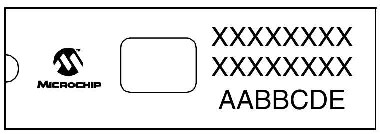
18-Lead SOIC (.300")



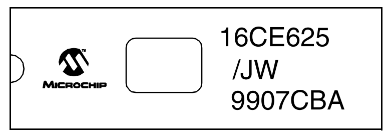
Example



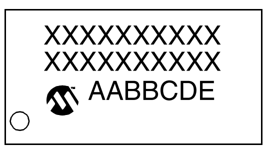
18-Lead CERDIP Windowed



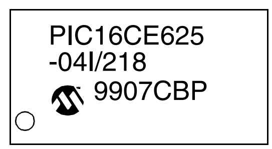
Example



20-Lead SSOP



Example



Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

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